WT02E40E BLE 5.3,802.15.4,WiFi6 Combo Module

WT02E40E Series are combo modules of a Nordic WiFi 6 nRF7002 SoC and a Nordic nRF5340 BLE 5.3 SoC. With a dual core ARM Cortex™ M33 MCU, up to 128MHz, quad radio-protocol transceivers, and various antenna options. They will be certified for BLE, 802.15.4, 2.4 GHz WiFi 6 and 5 GHz WiFi 6. It allows faster time to market with reduced development cost, especially for Matter applications.

No external component needed to minimize host PCB area: 40MHz, 32 MHz and 32.768 KHz, -40°C to +105°C, 20 PPM crystals are integrated. DCDC inductors for VDD and VDDH are integrated.

WiFi 6 Specifications
- Nordic nRF7002 SoC.
- Low-power and secure Wi-Fi for the IoT
- Supports IEEE 802.11 a/b/g/n/ac/ax
- Supports Target Wake Time (TWT), Orthogonal Frequency Division Multiple Access (OFDMA, Downlink and Uplink), BSS coloring
- WiFi CERTIFIED 6™, WiFi CERTIFIED™ a/b/g/n/ac, WiFi Enhanced Open™.
- Supports WPA3™, WPA2™, WPA™ - Personal and Enterprise, Protected Management Frames.
- Supports WMM®, WMM-Power Save, WiFi Agile Multiband™, WiFi Direct®.
- 2.4 GHz and 5 GHz dual-band or 2.4 GHz only
- Adjustable TX power from +5 to +19 dBm.
- Wi-Fi 6 Station (STA)
- 1 Spatial Stream (SS)
- 20 MHz channel bandwidth
- 64 QAM (MCS7), 86 Mbps PHY throughput
- Co-existence interfaces

BLE/802.15.4 Specifications:
- nRF5340 CLAA, dual core ARM® Cortex M33
- Application Core
  - 128/64 MHz Cortex M33 with FPU and DSP instructions
  - 1MB flash, 512KB RAM
  - 8KB 2-way set associate cache
  - ARM® TrustZone® Cryptocell-312 co-processor
- Network core:
  - 64 MHz Cortex M33 with 2KB instruction cache
  - 256KB flash, 64KB RAM

- Receiver Sensitivity: -98 dBm at 1Mbps.
- TX power: programmable +3dBm to -20dBm
- BLE 5.3 data rate: 2Mbps, 1Mbps, 500kbps, 125kbps.
- IEEE 802.15.4 data rate: 250 Kbps
- DCDC inductors for VDD, VDDH on board.
- Serial Wire Debug (SWD)
- Over-the-Air (OTA) firmware update
- 48 General purpose I/O pins
- USB 2.0 full speed (12 Mbps) controller
- QSPI interface
- Type 2 NFC-A tag with wake-on field, Touch-to-pair support
- Programmable peripheral interconnect (PPI)
- 12 bit/200 Ksps ADC, 8 configurable channels.
- Up to 3x pulse width modulator (PWM)
- Audio peripherals: I²S, digital microphone interface (PDM)
- 5 x 32 bit timers with counter mode
- Up to 3x SPI masters/3x SPI slaves
- Up to 2x I²C compatible 2-wire masters/slaves
- 2x UART (CTS/RTS)
- Quadrature Demodulator (QDEC)
- 2x real time counters (RTC)

Miscellaneous
- Hybrid pins: 16 castellated and 45 LGA.
- Operation voltage: 3.3V
- Pending Certifications: (BLE, 802.15.4, 2.4 GHz WiFi, 5GHz WiFi).
- QDID: 119517, 182626
- All modules support **approtect** features.

Model Summaries

| module	WT02E40E	WT02C40C	WT02E40F
SoCs	nRF5340+nRF7002	nRF5340+nRF7002	nRF5340+nRF7002
Size	16x26mm		16x31.6mm
Embedded crystals	40M+32M+32K	40M+32M+32K	40M+32M+32K
BT/WiFi Antenna	U.FL/u.FL	Chip/Chip	u.FL/PCB
Max TX, conducted, FCC			
Max TX, radiated, FCC			
Operating temp.	-40°C to +85°C	-40°C to +85°C	-40°C to +85°C
FCC ID			
ISED ID			
CE, RCM			
TELEC			
Evaluation board	EV-WT02E40E	EV-WT02C40C	EV-WT02E40F
Availability	Samples 04/2023	Samples 04/2023	Samples 04/2023

Table Of Contents

1. Introduction

WT02E40E Series are combo modules of a Nordic WiFi 6 nRF7002 SoC and a Nordic nRF5340 BLE 5.3 SoC. With a dual core ARM Cortex™ M33 MCU, up to 128MHz, quad radio-protocol transceivers, and various antenna options. They will be certified for BLE, 802.15.4, 2.4 GHz WiFi 6 and 5 GHz WiFi 6. It allows faster time to market with reduced development cost, especially for Matter applications.

WT02E40E Block Diagram

The following is a block diagram of WT02E40E. All required crystals are embedded. Connection to an external NFC (Near Field Communication) antenna is provided. There is an u.FL connector for an external Bluetooth/Thread antenna and a second u.FL connector for an external WiFi antenna. Sister modules use chips or PCB trace antennas.
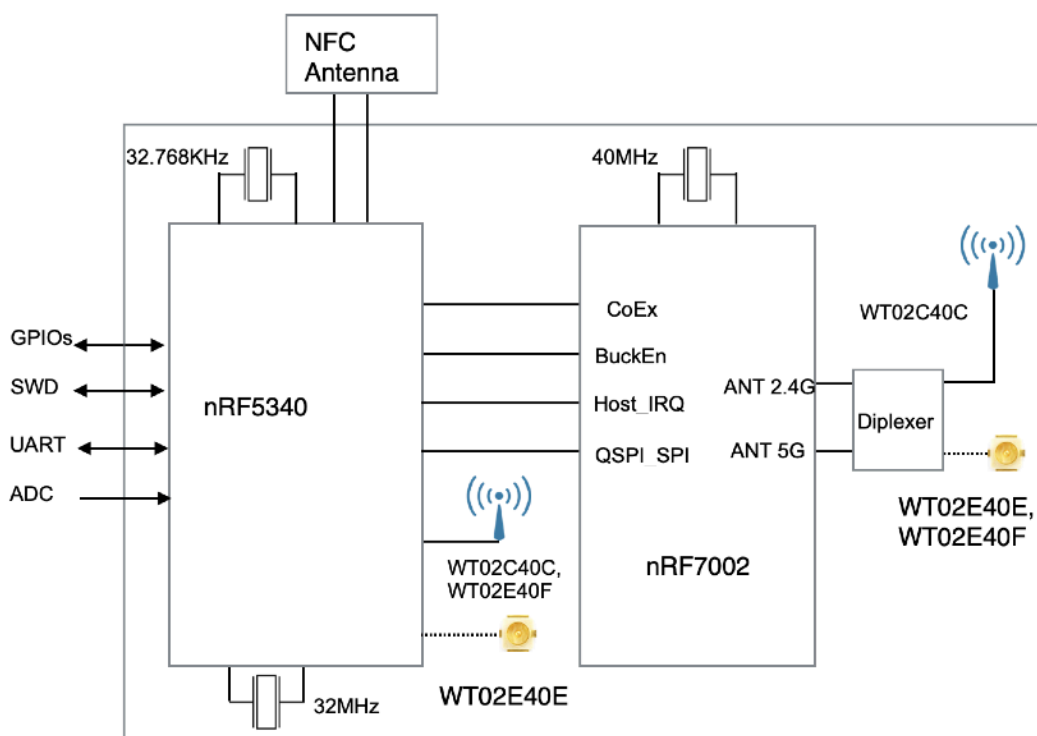
There are 3 modules in the WT02E40E Series.

We are integrating more components inside the module to make it "no external component is required". The soldering pads will not change. Please make sure you have clearance in the antenna area of the host board. Or, the antenna area is outside of the host board.

WT02E40E

- An nRF5340 SoC with dual core Cortex M33 MCU, up to 128 MHz

- An u.FL connector for an external BLE/Thread antenna.

- An nRF7002 WiFi 6 SoC supports IEEE 802.11 a/b/g/n/ac/ax for both 2.4 GHz and 5 GHz bands.

- An u.FL connector for an external WiFi antenna.

- Size: 16x26mm?

WT02E40F

- An nRF5340 SoC with dual core Cortex M33 MCU, up to 128 MHz

- An integrated high performance PCB trace antenna for BLE /802.15.4. This BLE PCB antenna is the same as that in the BT840F, BT840X, and BT40F.

- An nRF7002 WiFi 6 SoC supports IEEE 802.11 a/b/g/n/ac/ax for both 2.4 GHz and 5 GHz bands.

- An u.FL connector for an external WiFi antenna.

- Size: 16x31.6mm?

WT02C40C

- An nRF5340 SoC with dual core Cortex M33 MCU, up to 128 MHz

- An integrated chip antenna for BLE/802.15.4.

- An nRF7002 WiFi 6 SoC supports IEEE 802.11 a/b/g/n/ac/ax for both 2.4 GHz and 5 GHz bands.

- An integrated chip antenna for WiFi 6.

- Size: We are developing WT02C40C with chip antennas from multiple suppliers. We will offer one or more modules with the best WiFi performance. Module size to be determined.

2. Codes Development Using Nordic Tools

Development tools from Nordic and other third party development tools recommended by Nordic should be used.

Over-The-Air DFU

The nRF5340 is supported by an Over-The-Air Device Firmware Upgrade (OTA DFU) feature. This allows for in the field updates of application software and SoftDevice.

nRF Connect SDK

nRF Connect SDK is a scalable and unified software development kit for building products based on all our nRF52, nRF53 and nRF91 Series wireless devices. It offers developers an extensible framework for building size-optimized software for memory-constrained devices as well as powerful and complex software for more advanced devices and applications. It integrates the Zephyr RTOS and a wide range of samples, application protocols, protocol stacks, libraries and hardware drivers.

For developing Bluetooth Low Energy, Thread and Zigbee products, the nRF Connect SDK contains all needed software, including protocol stacks. For developing cellular IoT products it contains everything except the LTE modem firmware that must be downloaded separately from the nRF9160 SiP product page. See the cellular IoT software for more details.

nRF Connect SDK also offers an unique integration of HomeKit Accessory Development Kit for developing products using both HomeKit over Thread and HomeKit over Bluetooth Low Energy. It is a highly optimized solution that enables battery-powered products with both the HomeKit Accessory Protocol (HAP) and application firmware running on a single chip. MFi licensees can get access to the HomeKit repository by contacting us via Nordic DevZone private ticket.

nRF Connect SDK offers a single code base for all our devices and software components. It simplifies porting modules, libraries and drivers from one application to another, thus reducing development time. By enabling developers to pick and choose the essential software components for their application, high memory efficiency is guaranteed.

nRF Connect SDK is publicly hosted on GitHub, offers source code management with Git and has free SEGGER Embedded Studio IDE support. Nordic runs continuous integration tests on the nRF Connect SDK code to ensure robust and secure production quality code.

Development Tools

Nordic Semiconductor provides a complete range of hardware and software development tools for the nRF53 Series devices. nRF53 DK board is recommended for firmware development.

Nordic software development tools can be downloaded.

3. Product Descriptions

Block Diagram of nRF5340

The following is a block diagram of Nordic nRF5340 Bluetooth Low Energy (BLE) SoC. Please visit Nordic website for **full description and product specifications**.
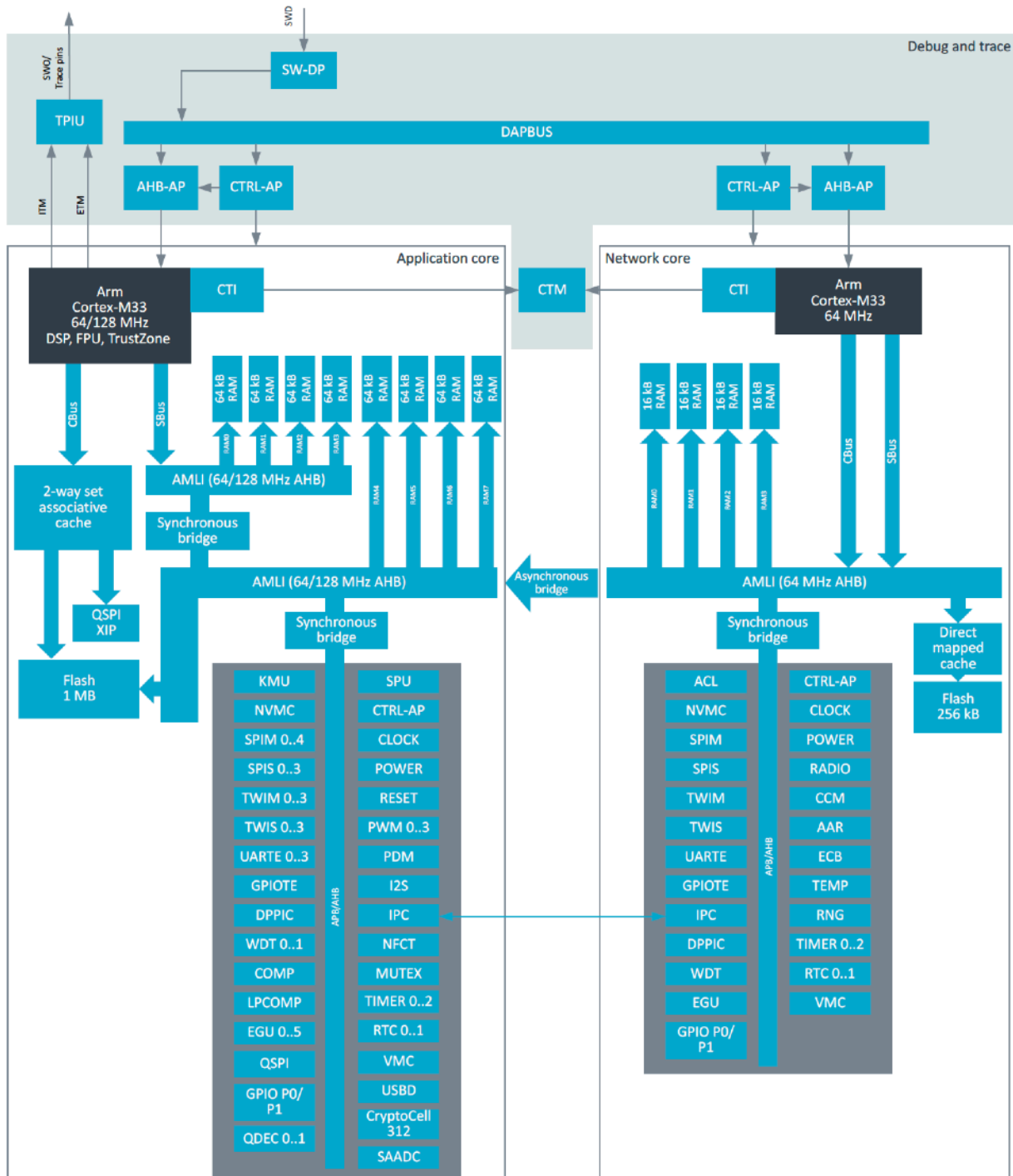
nRF5340 is a wireless ultra-low power multiple core System on Chip (SoC) integrating two fully programmable Arm Cortex M33 processors, advanced security features, a range of peripherals, and a multiprotocol 2.4 GHz

transceiver. The transceiver supports Bluetooth low energy, ANT™, and 802.15.4 and allows the implementation of proprietary 2.4 GHz protocols.

The two Arm Cortex M33 processors share the power, clock, and peripheral architecture with Nordic Semiconductor nRF51, nRF52, and nRF91 Series of PAN/LAN SoCs, ensuring minimal porting efforts. The application core is a full-featured Arm Cortex M33 processor including DSP instructions and FPU and running at up to 128 MHz with 1MB of flash and 512 KB of RAM. The option to run the application processor at 64 MHz allows the CPU to increase energy efficiency. The network core is an Arm Cortex M33 processor with a reduced feature set, designed for ultra-low power operation. It runs at a fixed 64 MHz frequency and contains 256 KB of flash and 64 KB of RAM.

The peripheral set offers a variety of analog and digital functionality enabling single chip implementation of a wide range of applications. Arm trustZone technology, Arm cryptoCell-312, and supporting blocks for ysytem protection and key management are embedded for the advanced security needed for IoT applications.

Mechanical Drawings

Soldering pads for WT02E40E is the same as that of the nRF5340 modules, BT40F and BT40N. Due to different antenna designs, the sizes of modules are different.

Two types of pins are available to meet different application requirements.

- 16 castellated pins for application needing limited number of IOs. SMT equipment is not required for soldering castellated pins.

- 45 LGA (Land Grid Array) pins to access all 48 GPIOs of nRF52840 when needed.

The following is WT02E40E mechanical drawings, top view.
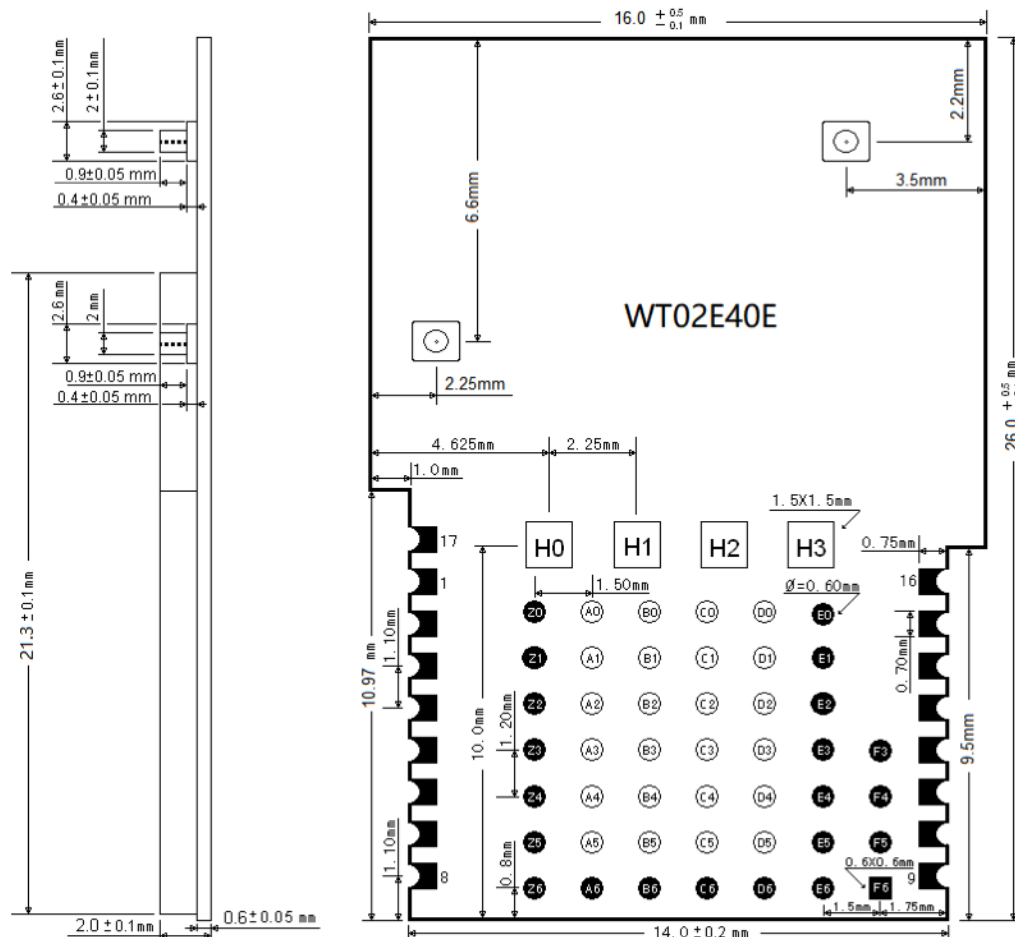
The following is WT02E40F mechanical drawings, top view.

WT02C40C mechanical drawings, top view, to be provided.

Pin Assignments of WT02E40E

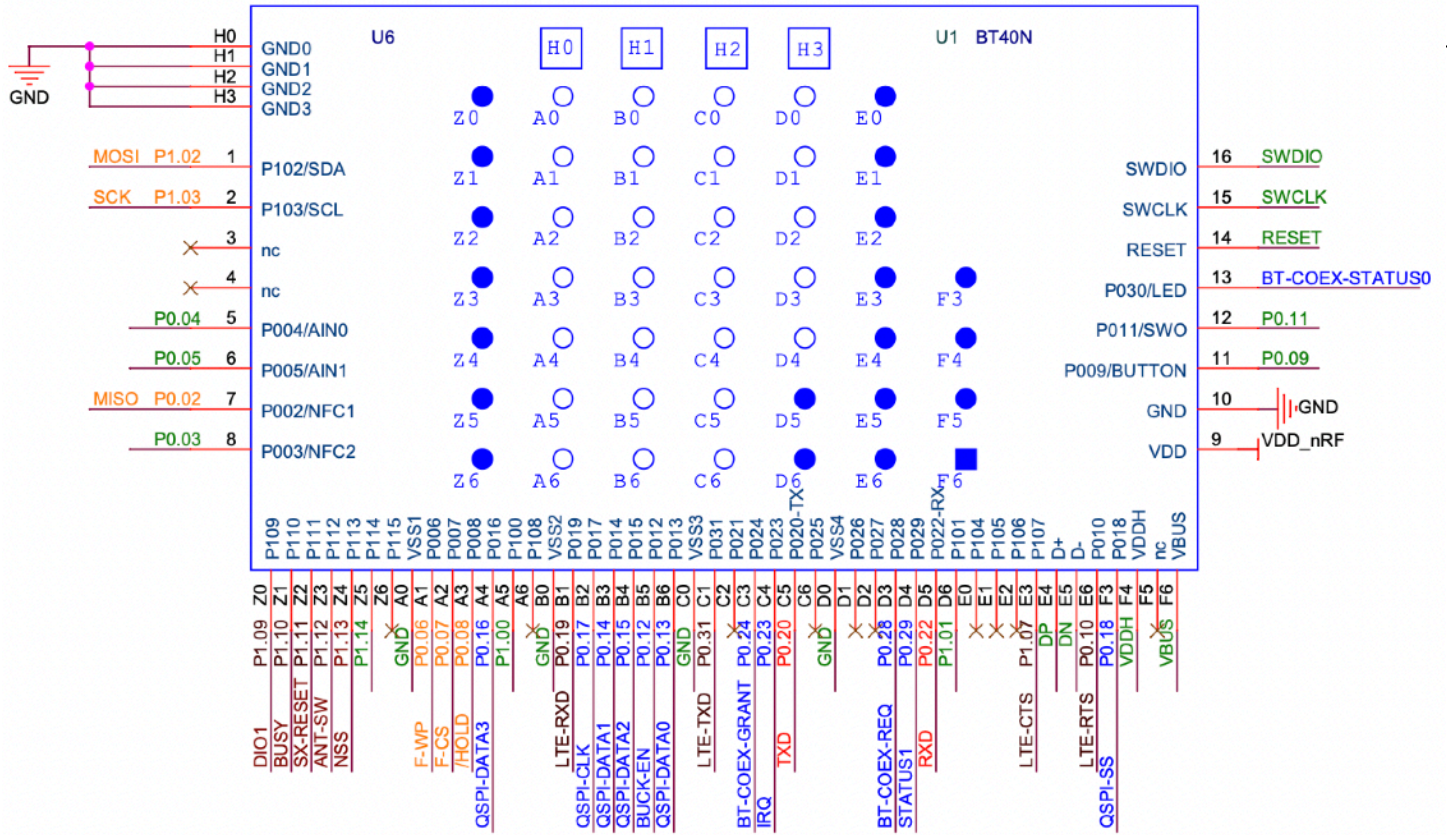The followings are WT02E40E pin assignment. Pin functions are in a table in next section. Please refer to Nordic **nRF5340 Product Specifications** for detailed descriptions and features supported.

BT840F, BT40F, and BT40N have compatible footprints. Pin assignments are below. Firmware configuration is required to upgrade module on the PCB.

FANSTEL

U6   U1 BT40N

| H0 | H1 | H2 | H3 |

GND

H0 — GND0
H1 — GND1
H2 — GND2
H3 — GND3

MOSI P1.02   1   P102/SDA
SCK   P1.03   2   P103/SCL
3   nc
4   nc
P0.04   5   P004/AIN0
P0.05   6   P005/AIN1
MISO P0.02   7   P002/NFC1
P0.03   8   P003/NFC2

Z0 A0 B0 C0 D0 E0
Z1 A1 B1 C1 D1 E1
Z2 A2 B2 C2 D2 E2
Z3 A3 B3 C3 D3 E3 F3
Z4 A4 B4 C4 D4 E4 F4
Z5 A5 B5 C5 D5 E5 F5
Z6 A6 B6 C6 D6 E6 F6

16   SWDIO   SWDIO
15   SWCLK   SWCLK
14   RESET   RESET
13   P030/LED   BT-COEX-STATUS0
12   P011/SWO   P0.11
11   P009/BUTTON   P0.09
10   GND   GND
9   VDD   VDD_nRF

Pin labels (bottom):
P109 P110 P111 P112 P113 P114 P115 VSS1 P006 P007 P008 P016 P100 P108 VSS2 P019 P017 P014 P015 P012 P013 VSS3 P031 P021 P024 P023 P020-TX P025 VSS4 P026 P027 P028 P029 P022-RX P101 P104 P105 P106 P107 D+ D- P010 P018 VDDH nc VBUS

Z0 Z1 Z2 Z3 Z4 Z5 Z6 A0 A1 A2 A3 A4 A5 A6 B0 B1 B2 B3 B4 B5 B6 C0 C1 C2 C3 C4 C5 C6 D0 D1 D2 D3 D4 D5 D6 E0 E1 E2 E3 E4 E5 E6 F3 F4 F5 F6

P1.09 P1.10 P1.11 P1.12 P1.13 P1.14 GND P0.06 P0.07 P0.08 P0.16 P1.00 GND P0.19 P0.17 P0.14 P0.15 P0.12 P0.13 GND P0.31 P0.24 P0.23 P0.20 GND P0.28 P0.29 P0.22 P1.01 P1.07 DP DN P0.10 P0.18 VDDH VBUS

DIO1 BUSY SX-RESET ANT-SW NSS F-WP F-CS /HOLD QSPI-DATA3 LTE-RXD QSPI-CLK QSPI-DATA1 QSPI-DATA2 BUCK-EN QSPI-DATA0 LTE-TXD BT-COEX-GRANT IRQ TXD BT-COEX-REQ STATUS1 RXD LTE-CTS LTE-RTS QSPI-SS

Pin Functions

The nRF5340 GPIO pins used to manage nRF7002 inside WT02E40E are in **blue** color in the **Descriptions** column. These pins are NC (No Connect) on the module.

BT40N/NE has the same soldering pads as BT40F. It uses 9 GPIO pins internally to control the power amplifier, nRF21540. These pins are described in red color in the **Descriptions** column. The SPI pins may be shared with other SPI devices. Avoid using these pins as GPIO pins if you need Bluetooth range upgrade.

BT840	52840		BT40/ BT40N	WT02E40E	nRF5340		
pin#	pin#	pin name	pin#	pin#	pin#	pin name	Descriptions
1	G1	P0.26/SDA	1	1	AE1	P1.02	GPIO, configured as I2C SDA on EV board
2	H2	P0.27/SCL	2	2	AF2	P1.03	GPIO, configured as I2C SCL on EV board
3	D2	P0.00/XL1	3	3	N1	NC	BT840F, external 32.768 KHz crystal connection; BT40F, NC, 32.768 KHz crystal embedded.
4	F2	P0.01/XL2	4	4	R1	NC	BT840F, external 32.768 KHz crystal connection; BT40F, NC, 32.768 KHz crystal embedded.
5	A12	P0.02/AIN0	5	5	V2	P0.04/AIN0	GPIO, Analog input
6	B13	P0.03/AIN1	6	6	Y2	P0.05/AIN1	GPIO, Analog input
7	L24	P0.09/NFC1	7	7	W1	P0.02/NFC1	GPIO, NFC antenna connection
8	J24	P0.10/NFC2	8	8	AA1	P0.03/NFC2	GPIO, NFC antenna connection
9	B1	VDD	9	9	A19	VDD	DC supply 1.7V to 3.6V
10	B7	GND	10	10	A25	VSS	Ground
11	T2	P0.11	11	11	AJ1	P0.09/MOSI	GPIO; BT40F, high speed SPI_MOSI.
12	AD22	P1.00	12	12	AK4	P0.11	GPIO
13	AD8	P0.13	13	NC	B24	P0.30	GPIO; NC for WT02E40E, used as COEX_Status 0 internally for nRF7002.
14	AC13	P0.18/RESET	14	14	AC31	/RESET	GPIO, reset with internal pull up, active low.
15	AA24	SWDCLK	15	15	W31	SWDCLK	Serial Wire Debug clock input
16	AC24	SWDIO	16	16	AA31	SWDIO	Serial Wire Debug I/O
Z0	B19	P1.11	Z0	Z0	AK26	P1.09	GPIO
Z1	B17	P1.12	Z1	Z1	R31	P1.10	GPIO
Z2	A16	P1.13	Z2	Z2	B20	P1.11	GPIO;
Z3	B15	P1.14	Z3	Z3	B18	P1.12	GPIO;
Z4	A14	P1.15	Z4	Z4	A17	P1.13	GPIO;
Z5	A20	P1.10	Z5	Z5	B16	P1.14	GPIO
Z6	R24	P1.06	Z6	Z6	B14	P1.15	GPIO, Connected to nRF21540 SCK pin internally for BT40N.
A0		GND	A0	A0	A25	VSS	Ground
A1	B11	P0.28/AIN4	A1	A1	AB2	P0.06/AIN2	GPIO, Analog input
A2	A10	P0.29/AIN5	A2	A2	AD2	P0.07/AIN3	GPIO, Analog input
A3	J1	P0.04/AIN2	A3	A3	AH2	P0.08/SCK	GPIO, BT840F, analog input; BT40F, high speed SPI clock
A4	K2	P0.05/AIN3	A4	A4	AL9	P0.16/IO3	GPIO, BT840F, analog input; BT40F, high speed SPI IO3
A5	M2	P0.07	A5	A5	M2	P1.00	GPIO
A6	P2	P1.08	A6	A6	AL23	P1.08	GPIO, Connected to nRF21540 MOSI pin internally for BT40N.
B0		GND	B0	B0		VSS	Ground

B1	AC21	P0.25	B1	B1	AL13	P0.19	GPIO
B2	B9	P0.30/AIN6	B2	B2	AK12	P0.17/SCK	GPIO, BT840F, analog input; BT40F, QSPI clock.
B3	A8	P0.31/AIN7	B3	B3	AK8	P0.14/IO1	GPIO, BT840F, analog input; BT40F, QSPI IO1
B4	L1	P0.06	B4	B4	AK10	P0.15/IO2	GPIO, NC for BT840X; BT40F, QSPI IO2
B5	N1	P0.08	B5	NC	AK6	P0.12/DCX	GPIO, NC for BT840X; BT40F, high speed SPI DCX; NC for WT02E40E, used internally as BUCKEN for nRF7002.
B6	V23	P1.03	B6	B6	AL5	P0.13/IO0	GPIO, BT40F, QSPI IO0
C0		GND	C0	C0		VSS	Ground
C1	AD20	P0.24	C1	NC	B22	P0.31	GPIO; NC for WT02E40E, used internally as IOVDD Control for nRF7002.
C2	AD18	P0.22	C2	C2	AL15	P0.21	GPIO; Connected to nRF21540 TX_EN pin internally for BT40N.
C3	AD12	P0.17	C3	NC	AL27	P0.24	GPIO; NC for WT02E40E, used internally as COES_Grant for RF7002.
C4	AD10	P0.15	C4	NC	AK20	P0.23	GPIO; NC for WT02E40E, used internally as Host IRQ for nRF7002.
C5	W24	P1.02	C5	C5	AK16	P0.20	GPIO
C6	U24	P1.04	C6	C6	AK28	P0.25/AIN4	GPIO, BT40F, analog input; Connected to nRF21540 MISO pin internally for BT40N.
D0		GND	D0	D0		VSS	Ground
D1	AC19	P0.23	D1	D1	AL29	P0.26/AIN5	GPIO, BT40F, analog input; Connected to nRF21540 PDN pin internally for BT40N.
D2	AC15	P0.19	D2	D2	AK30	P0.27/AIN6	GPIO, NC for BT840X/XE; BT40F, analog input; Connected to nRF21540 RX_EN pin internally for BT40N.
D3	AC11	P0.16	D3	NC	AE31	P0.28/AIN7	GPIO, BT40F, analog input; NC for WT02E40E, used internally as COEX-REQ for nRF7002.
D4	AC9	P0.14	D4	NC	U31	P0.29	GPIO; NC for WT02E40E, used internally as COEX_Status 1 for nRF7002.
D5	Y23	P1.01	D5	D5	AK18	P0.22	GPIO
D6	T23	P1.05	D6	D6	P2	P1.01	GPIO
E0	P23	P1.07	E0	E0	AL19	P1.04	GPIO; Connected to nRF21540 MODE internally for BT40N.
E1	AD16	P0.20	E1	E1	AK22	P1.05	GPIO; Connected to nRF21540 ANT-SEL internally for BT40N.
E2	AC17	P0.21	E2	E2	AL21	P1.06	GPIO; Connected to nRF21540 CSN pin internally for BT40N.
E3	R1	P1.09	E3	E3	AK24	P1.07	GPIO
E4	AD6	D+	E4	E4	B2	D+	USB D+
E5	AD4	D-	E5	E5	B4	D-	USB D-
E6	U1	P0.12	E6	E6	AK2	P0.10/MISO	GPIO, BT40F, high speed SPI MISO
F0			H0	H0			Ground pad
F1			H1	H1			Ground pad
F2			H2	H2			Ground pad
F3			H3	H3			Ground pad
			F3	F3	AK14	P0.18/CSN	GPIO, BT40F, QSPI chip select
F4	Y2	VDDH	F4	F4	E1	VDDH	High Voltage Power Supply, 2.5V to 5.5V
F5	AB2	DCCH	F5	F5	J1	NC	BT840F, DCDC converter output; BT40F, No connect, L,C circuit embedded.
F6	AD2	VBUS	F6	F6	A5	VBUS	5V DC power for USB 3.3V regulator

Using Internal Load Capacitors for the High Frequency Oscillator

The external load capacitors for the 32MHz crystal are not mounted. An Epson or equivalent +/-10 PPM crystal is connected to XC1 and XC2 pins. The Bluetooth signal frequencies are within specifications if the internal load capacitors are not enabled. Use the following procedures to set the internal load capacitors to ?? pF, the Bluetooth signal frequency is measured to be within 5 PPM at 25°C.

The internal load capacitors can be programmed from 7.0 pF to 20 pF in 0.5 pF steps. The addresses and description of registers for programming the value of load capacitors are from the Nordic nRF5340 Product Specifications.

Base address	Domain	Peripheral	Instance	Secure mapping	DMA security	Description	Configuration
0x50004000	APPLICATION	OSCILLATORS	OSCILLATORS : S	US	NA	Oscillator configuration	
0x40004000			OSCILLATORS : NS				

Programmable capacitance of XC1 and XC2

Bit number		31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0
ID		B A A A A A
Reset 0x00000000		0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0

ID	R/W	Field	Value ID	Value	Description
A	RW	CAPVALUE			Value representing capacitance, calculated using provided equation
B	RW	ENABLE			Enable on-chip capacitors on XC1 and XC2
			Disabled	0	Capacitor disabled (use external caps)
			Enabled	1	Capacitor enabled

Register	Offset	Security	Description	
XOSC32MCAPS	0x5C4		Programmable capacitance of XC1 and XC2	Retained
XOSC32KI.BYPASS	0x6C0		Enable or disable bypass of LFCLK crystal oscillator with external clock source	Retained
XOSC32KI.INTCAP	0x6D0		Control usage of internal load capacitors	Retained

To program the load capacitance, settings in the file cpu_app prj.conf:

CONFIG_SOC_ENABLE_LFXO=y
CONFIG_SOC_LFXO_CAP_INT_7PF=y
CONFIG_SOC_HFXO_CAP_INTERNAL=y
CONFIG_SOC_HFXO_CAP_INT_VALUE_X2=25
CONFIG_BUILD_WITH_TFM=y

X2=14 7pf   0x400045c4=0x102
X2=15 7.5pf   0x400045c4=0x103
X2=16 8pf   0x400045c4=0x104
X2=17 8.5pf   0x400045c4=0x105
X2=18 9pf   0x400045c4=0x106
X2=19 9.5pf   0x400045c4=0x107
X2=20 10pf   0x400045c4=0x107
X2=21 10.5pf 0x400045c4=0x108

X2=22 11pf   0x400045c4=0x109   //BT40 default
X2=23 11.5pf 0x400045c4=0x10A
X2=24 12pf   0x400045c4=0x10B
X2=25 12.5pf 0x400045c4=0x10C //recover default
X2=26 13pf   0x400045c4=0x10D
X2=27 13.5pf 0x400045c4=0x10E
X2=28 14pf   0x400045c4=0x10F
X2=29 14.5pf 0x400045c4=0x110
X2=30 15pf   0x400045c4=0x111
X2=31 15.5pf 0x400045c4=0x112 //BC40 default
X2=32 16pf   0x400045c4=0x113

…….

Alternatively, the load capacitance can be programmed using commands.

```
C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 0000010C                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 00000102                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 00000102                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 00000102                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 0000010B                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 0000010D                          |....|

C:\Users\Leo>nrfjprog --memrd 0x500045c4
0x500045C4: 0000010C                          |....|

C:\Users\Leo>
```

Mounting WT02E40F Module on the Host PCB

The following figure shows recommended mounting of WT02E40F module on the host PCB.

- For the best Bluetooth range performance, the antenna area of module shall extend 9.8 mm outside the edge of host PCB board, or 9.8 mm outside the edge of a ground plane.

- The next choice is to place a module on a corner of host PCB, the antenna area shall extend 9.8 mm from the edge of ground plane. Ground plane shall be at least 5 mm from the edge of the antenna area of module.

- We don't recommend mounting WT02E40F module in the middle of a host PCB.
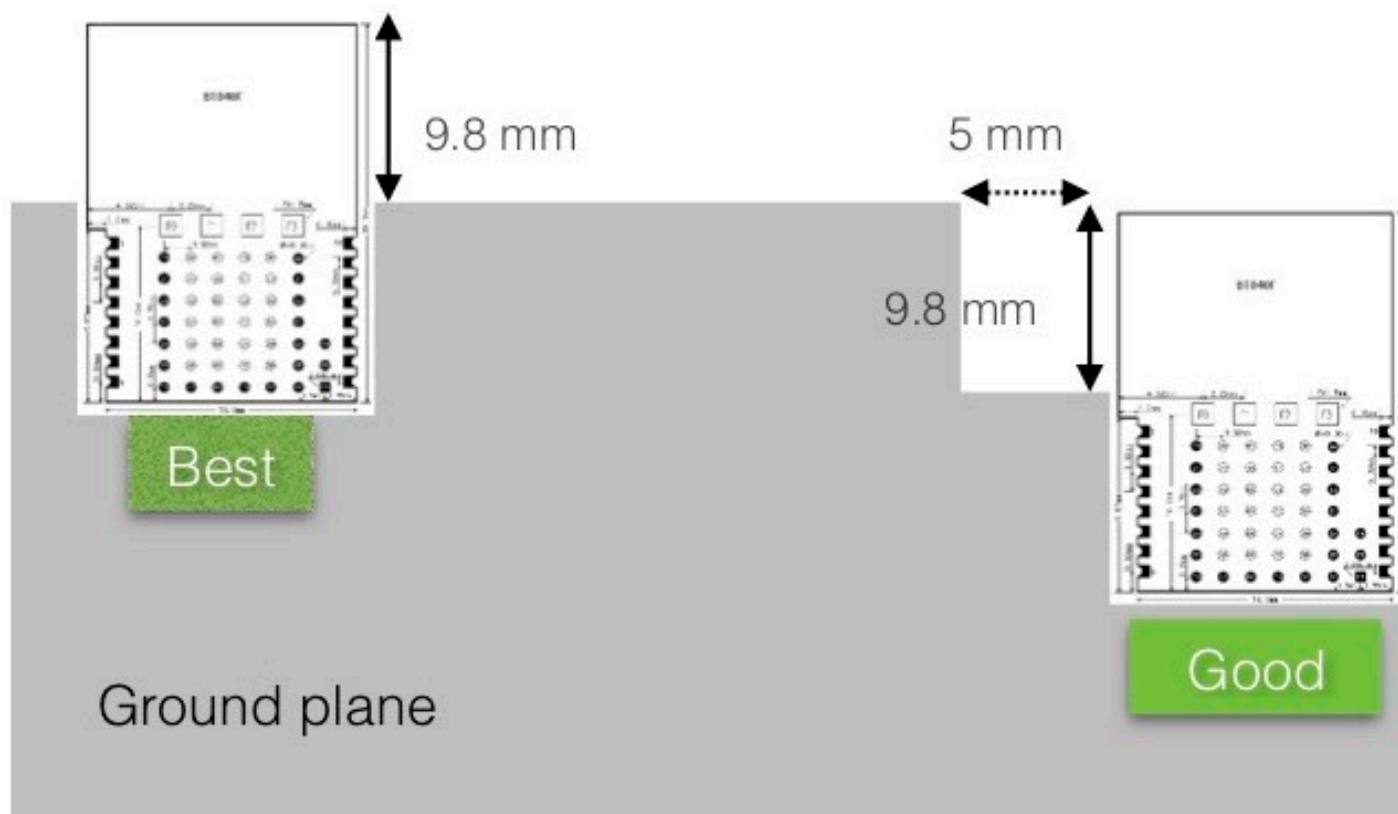
For the best Bluetooth and WiFi range performance, keep all external metal at least 30mm from the antenna area.

Host Board Design for Low Cost or Long Range

On nRF53 series SoCs, Nordic offers various memory options and protocol supports. Fanstel offers various antenna and power amplifier options. A host board can be designed to accommodate these nRF53 modules. Our suggestions for host PCB design:

- use a 4 or more layers PCB.

- Use library component from EV-WT02E40F Gerber files. They can be downloaded from http://www.fanstel.com/download-document/. It has 16 castellated pins plus 45 LGA pins.

- WT02E40F soldering pad footprint is compatible with that of BT40F and BT40N (nRF5340+nRF21540).

- As much ground plane under WT02E40F, on top side of host PCB as possible. Use EV-WT40E40F Gerber files as an example.

4. WT02E40E Evaluation Board

An evaluation board consists of the followings:

• Mini USB cable

• Evaluation board

• 10-conductor cable for connection to Nordic nRF53 DK (DK is not included)

The EV board can be programmed by using a Nordic nRF53 DK board, connected as below. (Photo to be updated)

3. 10-conductor cable
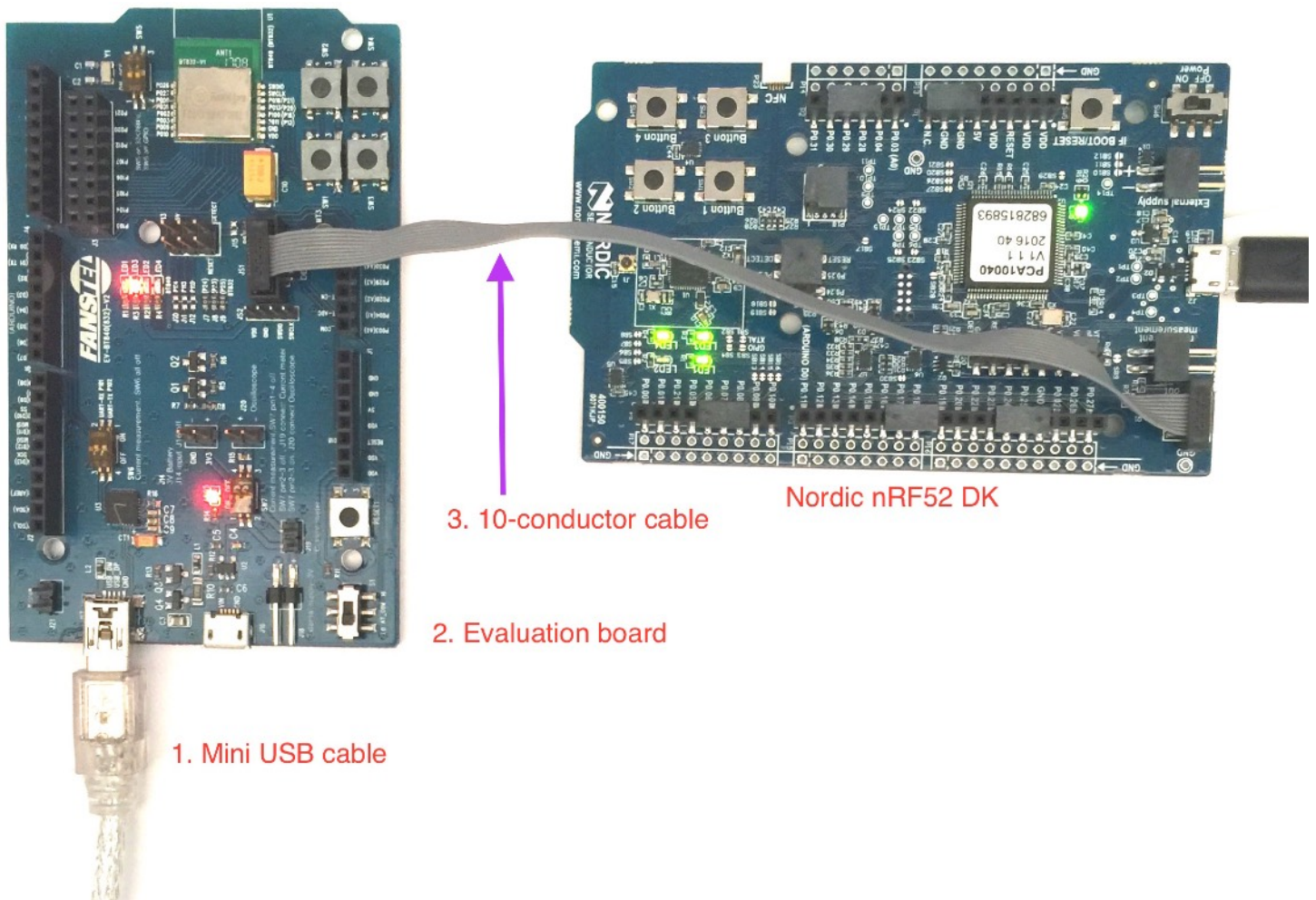
Nordic nRF52 DK

2. Evaluation board

1. Mini USB cable

Nordic Development Tools

A Nordic nRF5340 DK is recommended for programming this evaluation board. Visit Nordic website for **nRR5340 DK description and product brief**.

Many application examples can be downloaded from Nordic website.

Some firmware, Android OS, and iOS app codes can be downloaded from **Bluetooth 5 Codes section** of this Fanstel webpage.

http://www.fanstel.com/download-document/

BT40 firmware can be used in all nRF5340 modules without power amplifier, e.g., WT02E40F, WT02E40E, WT02C40C, BT40F and BT40E.

Android OS Apps

The following Android OS apps are available for download from Google Play Store:
BlueNor nrf5x: to use with Bluetooth 5 stacks, AT commands, or Slave firmware. Master firmware does not connect to a smartphone. Source codes can be downloaded from http://www.fanstel.com/download-document/

BlueNor Mesh: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received. Source codes will be uploaded to Fanstel website when supporting Bluetooth 5.

iOS Apps

The following iOS apps can be downloaded from Apple APP Store.

BlueNor Mesh: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received.
BlueNor nrf5x firmware, apps, and source codes will be uploaded when ready.

EV-WT02E40E EvaluationBoard Schematics

Evaluation board **EV-WT02E40F schematics and Gerber files** is available at Fanstel website.

Evaluation board can be used as a reference design for using modules. EV-WT02E40E is designed for the WT02E40E soldering pads with 61 pins. This EV board can also be used for WT02C40C and WT02E40F modules.

Suggestion for Battery Power Application

Standby current consumption is important for battery-powered product. To reduce host board area, the followings are embedded in modules:

• 32 MHz, 20PPM main crystal.

• 32.768 KHz, 20PPM sleep crystal and load capacitors.

• 40 MHz crystal for nRF7002.

• Inductors and capacitors required for VDD power supply DC to DC converter.

• Inductors and capacitors required for VDDH power supply DC to DC converter.

No external component is required. DCDC converter shall be enabled to reduce power consumption.

5. Miscellaneous

Soldering Temperature-Time Profile for Re-Flow Soldering

Maximum number of cycles for re-flow is 2. No opposite side re-flow is allowed due to module weight.
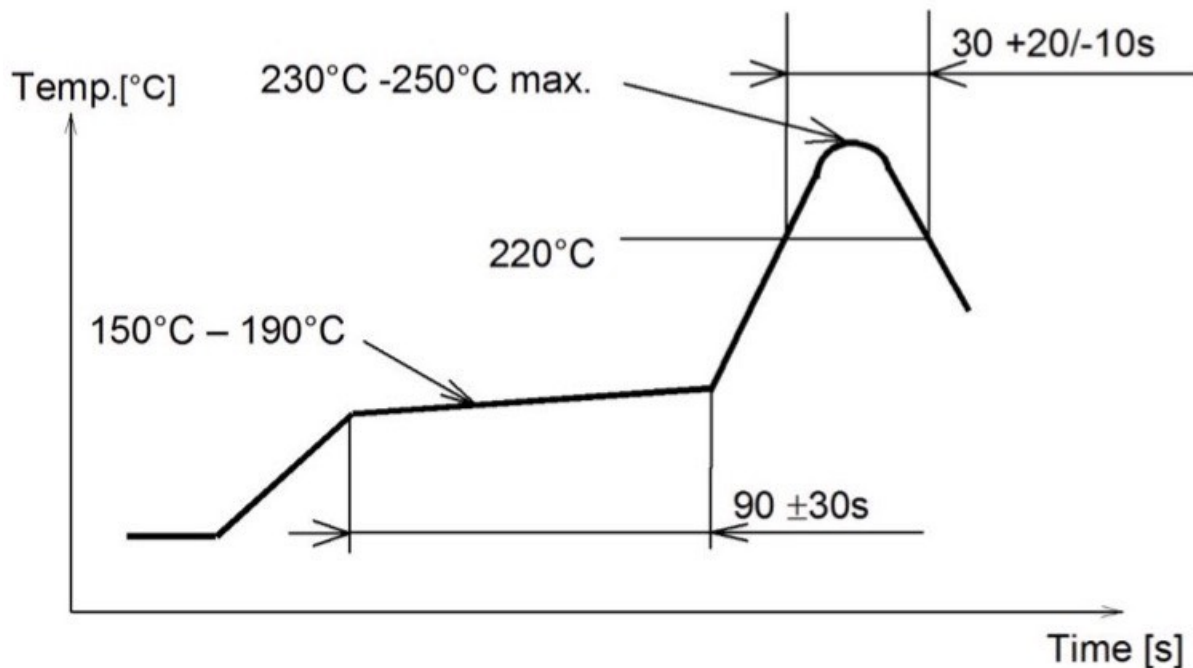
Cautions, Design Notes, and Installation Notes

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

Design Notes

(1) Follow the conditions written in this specification, especially the control signals of this module.

(2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).

(3) This product should not be mechanically stressed when installed.

(4) Keep this product away from heat. Heat is the major cause of decreasing the life of these products.

(5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.

(6) The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.

(7) this product away from other high frequency circuits.

Notes on Antenna and PCB Layout

(1) Don't use a module with internal antenna inside a metal case.

(2) For PCB layout:

- Avoid running any signal line below module whenever possible,
- No ground plane below antenna,
- If possible, cut-off the portion of main board PCB below antenna.

Installation Notes

(1) Reflow soldering is possible twice based on the time-temperature profile in this data sheets. Set up the temperature at the soldering portion of this product according to this reflow profile.

(2) Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.

(3) Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.

(4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.

(5) This product should not be mechanically stressed or vibrated when reflowed.

(6) If you want to repair your board by hand soldering, please keep the conditions of this chapter.

(7) Do not wash this product.

(8) Refer to the recommended pattern when designing a board.

(9) Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.

Usage Condition Notes

(1) Take measures to protect the unit against static electricity. If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation before assembly on the final products.

(2) Do not use dropped products.

(3) Do not touch, damage or soil the pins.

(4) Follow the recommended condition ratings about the power supply applied to this product.

(5) Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB

(6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.

(7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

Storage Notes

(1) The module should not be stressed mechanically during storage.

(2) Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:

- Storage in salty air or in an environment with a high concentration of corrosive gas.

- Storage in direct sunlight

- Storage in an environment where the temperature may be outside the range specified.

- Storage of the products for more than one year after the date of delivery storage period.

(3) Keep this product away from water, poisonous gas and corrosive gas.

(4) This product should not be stressed or shocked when transported.

(5) Follow the specification when stacking packed crates (max. 10).

Safety Conditions

These specifications are intended to preserve the quality assurance of products and individual components. Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

(1) Ensure the safety of the whole system by installing a protection circuit and a protection device.

(2) Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a dual fault causing an unsafe status.

Other Cautions

(1) This specification sheet is copyrighted. Reproduction of this data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices.

(2) Do not use the products for other purposes than those listed.

(3) Be sure to provide an appropriate failsafe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.

(4) This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.

(5) These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.

- In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.

- In direct sunlight, outdoors, or in a dusty environment

- In an environment where condensation occurs.

- In an environment with a high concentration of harmful gas.

(6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.

(7) When you have any question or uncertainty, contact Fanstel.

Packaging and Lot Number

Production modules are delivered in reel, 1000 modules in each reel. Lot number for modules made after May 2019, can be used to track silicon version of SoC, module PCB version, and production test code version.

FANSTEL

(K) Cust. PO:2630427

(4K) Cust. PO line:00003

(P) Cust. P/N : 1914-1019-2-ND

(1T) Lot :D0V218B-0000000

(Q) QTY :1000

(1P) MFG P/N : BT840F

(6D) Ship Date :20190522

(9D) Date : 1920

(4L) COO: CN

MSL 3/260℃
(E) e4
RoHS

Lot: **D0 V2 18B - 00 00 000**

D0: 2 digits, version number of SoC.
V2: 2 digits, version number of module PCB.
18B: the first 2 digits for production test codes released year and the last digit for month in hex format. A=October, B=November, C=December. 18B was released in November 2018.
00 00 000, 7 digits, reserved for 2nd SoC for modules with 2 SoCs.

FCC LABEL

The Original Equipment Manufacturer (OEM) must ensure that the OEM modular transmitter must be labeled with its own FCC ID number. This includes a clearly visible label on the outside of the final product enclosure that displays the contents shown below. If the FCC ID is not visible when the equipment is installed inside another device, then the outside of the device into which the equipment is installed must also display a label referring to the enclosed equipment

The end product with this module may subject to perform FCC part 15 unintentional emission test requirement and be properly authorized.

This device is intended for OEM integrator only.

Revision History

• Jan. 2023, Ver. 0.90: Initial draft release

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